

4 wire method and Blow up Experiment

| Res | | 13mil Vias | 100mil | 20mil | 10mil | 8mil | 6mil |
|-----------|------|------------|--------|-------|-------|-------|-------|
| 2-wire | ohm | 0.95 | 0.98 | 1.07 | 1.11 | 0.82 | 0.86 |
| 4-wire | mohm | 7.73 | 4.55 | 21.81 | 44.66 | 56.25 | 79.26 |
| estimated | mohm | | 4.4 | 22 | 44 | 55 | 73.3 |

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|---------|------|-------|
| BlowUp | 6mil | 20mil |
| warm | 2A | 4A |
| hot | 3A | 6A |
| smoking | 4A | 9A |

1. Estimate resistance: The trace is about $L = 880\text{mil}$, the $R_{\text{square}} = 0.5\text{mohm/square}$,
R is estimated as $(L/\text{width}) * R_{\text{square}}$ as in spread sheet.
2. So What Question: The spread sheet tells that when measuring small resistance, using 4-wire method is a necessary. If 2-wire method used directly, the resistance is largely obfuscated by the connect resistance. Using 4-wire method can measure the resistance.
3. The maximum IPC current for 20mil under 20 Fahrenheit is 3A, the maximum IPC current for 6mil under 20 Fahrenheit is 1A. The observation is shown in spreadsheet.
4. Recommendation I feel safe for using 6mil maximumly is 1A, for 20mil is 3A.

Solder Practice:

5. A picture of board is added at next page. (The 0402 part is soldered at R56)
6. The easiest to solder is the column with thermal relief. The middle part which have right pads embedded in part of a plane is most difficult to solder. The left column is relatively easy to solder as well. The trick I use is shown in the video, first put a little solder on the pad and use solder flux. Then place the part and melt the solder to fix the part.
7. Using solder flux is very important, it gives the purity and remove any oxides. It prevents the oxides are formed when the metal is exposed to air.
8. When removing the parts, it is needed to raise the temperature. After removing the part, using the copper wire and solder flux to clean the pad at high temperature.

